

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application.

Listing of Claims:

1-7, 9-24. (canceled)

8. (currently amended) ~~The leadframe according to Claim 1 wherein~~ A leadframe for use in the assembly of integrated circuit chips, comprising:

a base metal structure having an adherent layer of nickel covering said base metal;

an adherent film of palladium on said nickel layer; and

an adherent layer of palladium on said palladium film, selectively covering areas of said leadframe suitable for bonding wire attachment and solder attachment said palladium layer provides visual distinction to the areas covered by said layer over the areas of said palladium film uncovered by said palladium layer.